**There were four talks of AIDA-2020 participants:
1. AGH-UST, M. Idzik, work is focused on FLAME - readout ASIC for LumiCal, 2 ASICs with main FLAME functionalities are fabricated, the works on test setups and PCBs are ongoing. In 1-2 months the tests should start. In case of positive verification next submission will be 16-channel FLAME.
2. DESY, S. Schuwalow, presently the work is concentrated in R&D on fan-out technology, and in particular on bumped fan-out. The main advantage is easy disassembling since the contact is provided by pressure. the studies are ongoing, problems may appear for oxidized sensors.
3. IFJPAN,. L. Zawiejski, works on back-end electronics for LumiCal started. The first step is to simulate data flow fro the FLAME and to process it. Evaluation FPGA board have been bought for this aim and the works are ongoing
4. TAU, Y. Benhammou, works on thin sensor module are proceeding well. The first stage i.e. construction of thin, below 1 mm, module comprising carbon envelope, old LumiCal sensors and kapton fan-out already successful and test-beam done.
Studies on tab-bonding are ongoing. In parallel, studies on edgeless sensors (with Hamamatsu) started.

And two non-AIDA-2020 related presentations:
5. PUC, A. Abusleme, works on BeamCal readout slowed down, mainly because of funding problems. But Angel continues the efforts both regarding getting funds and Cadence availability, hoping to overcome the problems. The question remains how to use his (group) time efficiently in this not easy time. I think we (Angel + me(LumiCal FE) + Sergiej, Wolfgang (beamCal sensors)) should think about it and make separate skype/vidyo discusssion... ?
6. UC SantaCruz, B. Schumm, works on rad-hard sensors for BeamCal are ongoing, Recently various Si sensors were irradiated up to ~300Mrads, very good charge collection is observed for p-type float-zone Si sensors. Bruce argues that even the continuously growing leakage current is not a big problem since it could be cured by standard cooling.**

**Marek**